THE DATASHEET OF

RC4580QDRQ1

www.win-source.net 0086-755-83957316

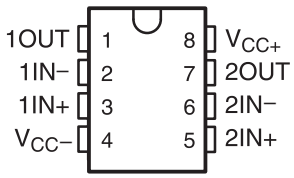
DUAL AUDIO OPERATIONAL AMPLIFIER

Check for Samples: RC4580-Q1

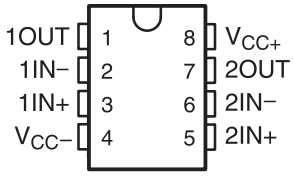
FEATURES

- **Qualified for Automotive Applications**
- **AEC-Q100 Qualified With the Following Results:**
  - **Device Temperature Grade 1: –40°C to 125°C Ambient Operating Temperature Range**
  - **Device HBM ESD Classification Level H2**
  - **Device CDM ESD Classification Level C3B**
- **Operating Voltage . . . ±2 V to ±18 V**
- **Low Noise Voltage . . . 0.8 µVrms (TYP)**
- **Wide GBW . . . 12 MHz (TYP)**
- **Low THD . . . 0.0005% (TYP)**
- **Slew Rate . . . 5 V/µs (TYP)**
- **Suitable for Automotive Applications Such As Audio Preamplifier, Active Filter, Headphone Amplifier, Industrial Measurement Equipment**
- **Drop-In Replacement for NJM4580**
- **Pin and Function Compatible With LM833, NE5532, NJM4558/9, and NJM4560/2/5**

D PACKAGE
SOIC – 8
(TOP VIEW)



PW PACKAGE
TSSOP – 8
(TOP VIEW)



DESCRIPTION

The RC4580-Q1 device is a dual operational amplifier that is designed optimally for audio applications, such as improving tone control. It offers low noise, high gain bandwidth, low harmonic distortion, and high output current. All of these features make the device ideally suited for audio electronics, such as audio preamplifiers and active filters, as well as industrial measurement equipment. When high output current is required, the RC4580-Q1 device can be used as a headphone amplifier. Due to its wide operating supply voltage, the RC4580-Q1 device can also be used in low-voltage applications.

ORDERING INFORMATION(1)

T_A	PACKAGE(2)		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 125°C	SOIC – D	Reel of 2000	RC4580QDRQ1	R4580Q
–40°C to 125°C	TSSOP - PW	Reel of 2000	RC4580QPWRQ1	R4580Q

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.
(2) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of the Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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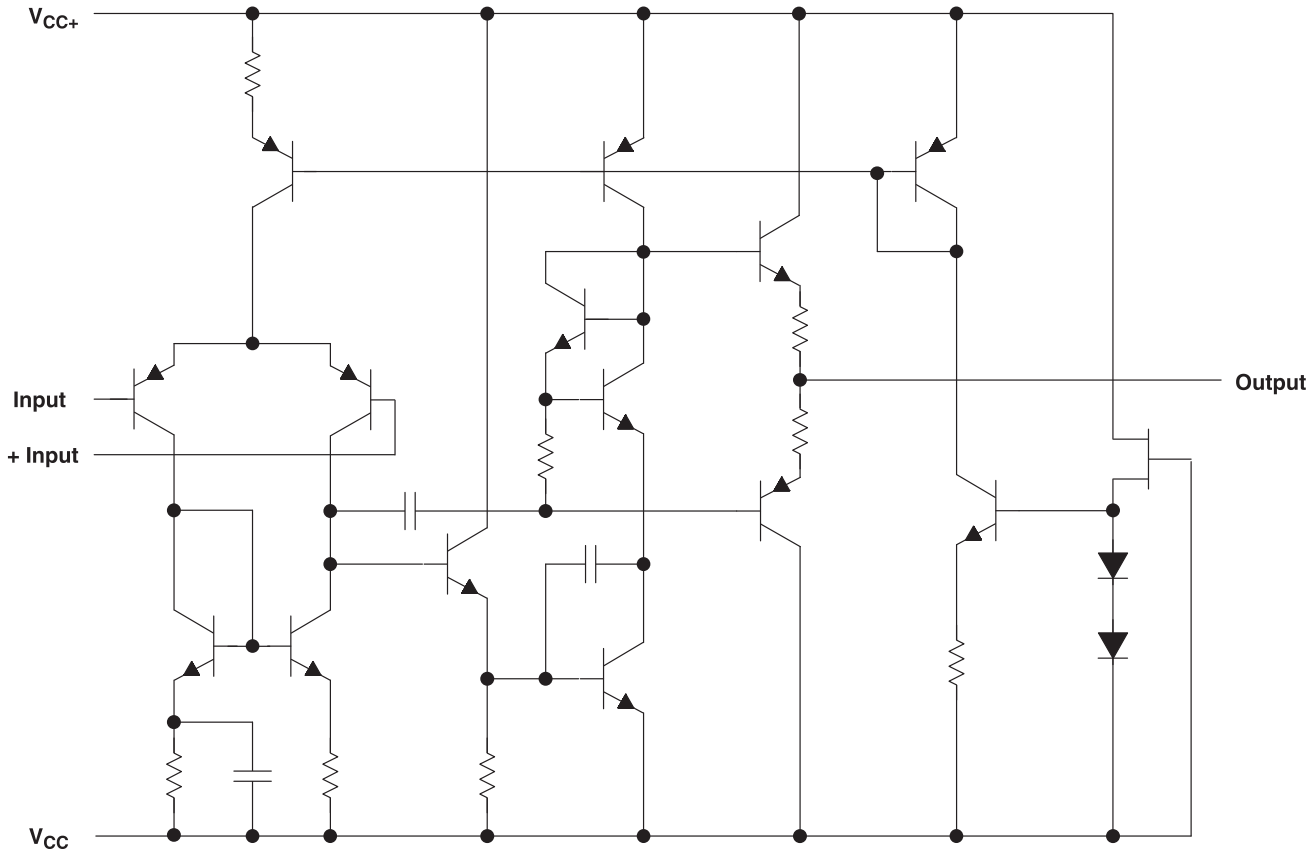
This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

Figure 1. EQUIVALENT SCHEMATIC



ABSOLUTE MAXIMUM RATINGS(1)

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V_{CC}	Supply voltage		±18	V
	Input voltage (any input)		±15	V
V_{ID}	Differential input voltage		±30	V
	Output current		±50	mA
T_A	Ambient temperature range	–40	125	°C
T_{stg}	Storage temperature range	–60	125	°C
Electrostatic Discharge (ESD) Ratings	Human-body model (HBM) AEC-Q100 Classification Level H2		2	kV
	Charged-device model (CDM) AEC-Q100 Classification Level C3B		750	V

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

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THERMAL INFORMATION

THERMAL METRIC[1]		RC4580-Q1		UNIT
		D (8 PINS)	PW (8 PINS)	
θ_{JA}	Junction-to-ambient thermal resistance	109	163	°C/W
θ_{JCtop}	Junction-to-case (top) thermal resistance	55.7	38	
θ_{JB}	Junction-to-board thermal resistance	49	90.6	
ψ_{JT}	Junction-to-top characterization parameter	10.6	1.3	
ψ_{JB}	Junction-to-board characterization parameter	48.6	88.9	
θ_{JCbot}	Junction-to-case (bottom) thermal resistance	n/a	n/a	

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, SPRA953.

RECOMMENDED OPERATING CONDITIONS

		MIN	MAX	UNIT
V_{CC+}	Supply voltage	2	16	V
V_{CC-}		–2	–16	
V_{ICR}	Input common-mode voltage range	–13.5	13.5	V
T_A	Operating free-air temperature	–40	125	°C

ELECTRICAL CHARACTERISTICS

$V_{CC\pm}$ = ±15 V, T_A = –40°C to 125°C (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_{IO}	Input offset voltage	R_S = < 10 kΩ		0.5	3	mV
I_{IO}	Input offset current			5	200	nA
I_{IB}	Input bias current			100	500	nA
A_{VD}	Large-signal differential voltage amplification	R_L ≥ 2 kΩ, V_O = ±10 V	90	110		dB
V_{CM}	Output voltage swing	R_L ≥ 2 kΩ	±12	±13.5		V
V_{ICR}	Common-mode input voltage		±12	±13.5		V
CMRR	Common-mode rejection ratio	R_S ≤ 10 kΩ	80	110		dB
k_{SVR}	Supply-voltage rejection ratio[1]	R_S ≤ 10 kΩ	80	110		dB
I_{CC}	Total supply current (all amplifiers)			6	9	mA

(1) Measured with $V_{CC\pm}$ varied simultaneously

OPERATING CHARACTERISTICS

$V_{CC\pm}$ = ±15 V, T_A = –40°C to 125°C (unless otherwise noted)

PARAMETER		TEST CONDITIONS	TYP	UNIT
SR	Slew rate at unity gain	R_L ≥ 2 kΩ	5	V/μs
GBW	Gain-bandwidth product	f = 10 kHz	12	MHz
THD	Total harmonic distortion	V_O = 5 V, R_L = 2 kΩ, f = 1 kHz, A_{VD} = 20 dB	0.0005%	
V_n	Equivalent input noise voltage	RIAA, R_S ≤ 2.2 kΩ, 30-kHz LPF	0.8	μVrms

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TYPICAL CHARACTERISTICS

MAXIMUM OUTPUT VOLTAGE SWING vs LOAD RESISTANCE

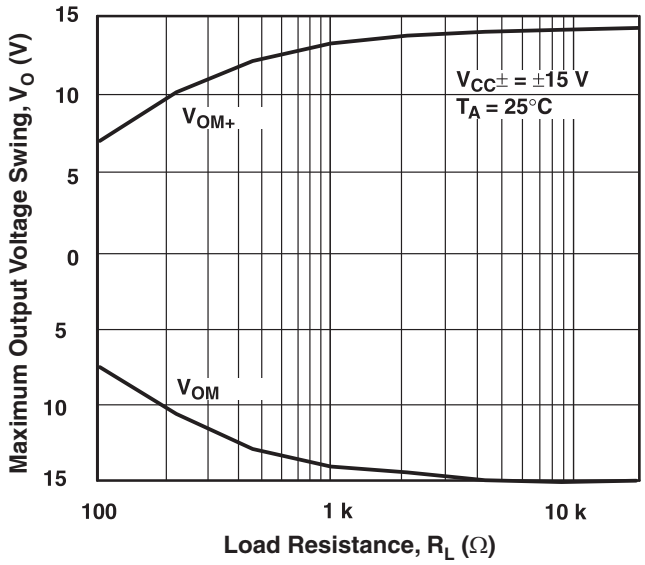

Figure 2.

MAXIMUM OUTPUT VOLTAGE SWING vs FREQUENCY

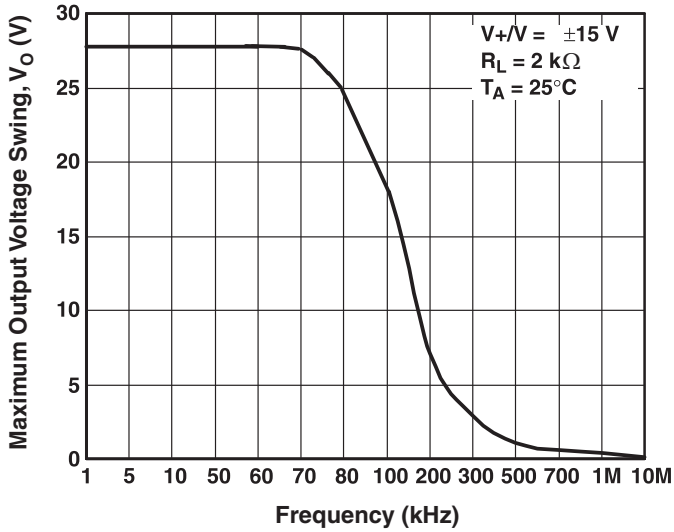

Figure 3.

OUTPUT VOLTAGE SWING vs OUTPUT CURRENT

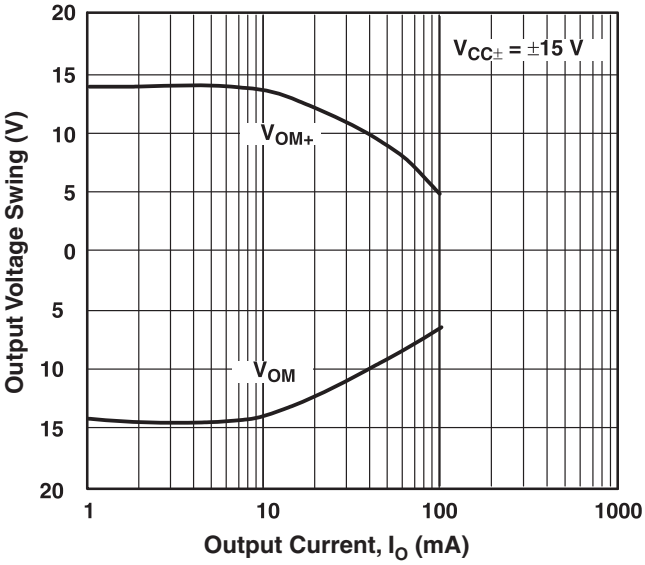

Figure 4.

EQUIVALENT INPUT NOISE VOLTAGE vs FREQUENCY

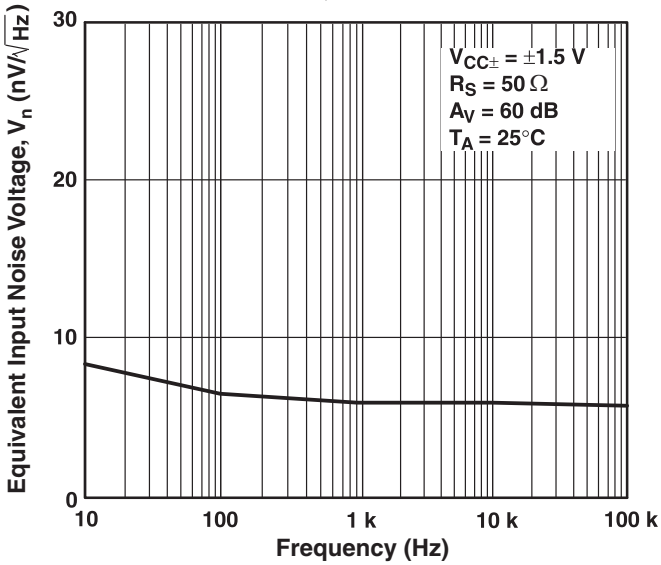

Figure 5.

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TYPICAL CHARACTERISTICS (continued)

OPERATING CURRENT vs TEMPERATURE

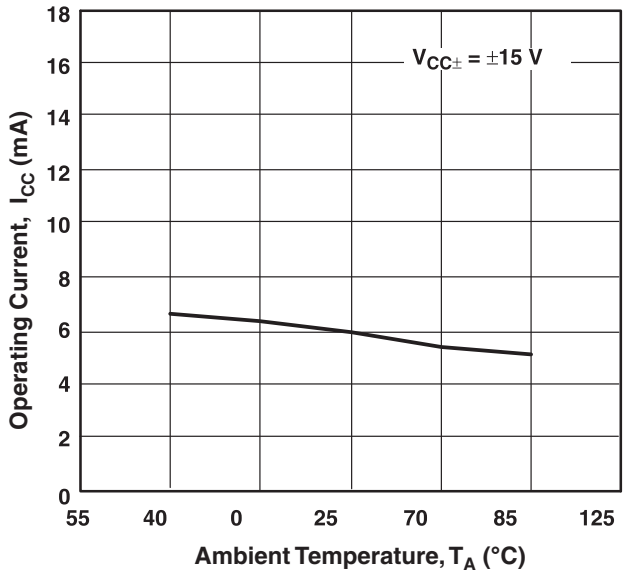

Figure 6.

OUTPUT VOLTAGE SWING vs TEMPERATURE

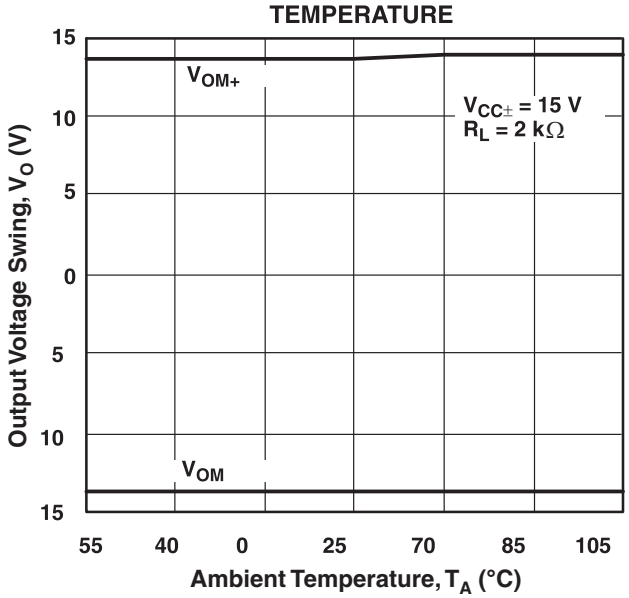

Figure 7.

INPUT OFFSET VOLTAGE vs TEMPERATURE

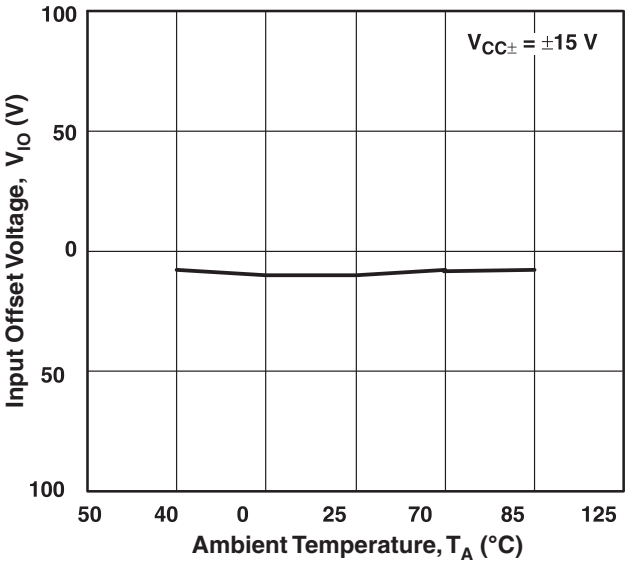

Figure 8.

INPUT BIAS CURRENT vs TEMPERATURE

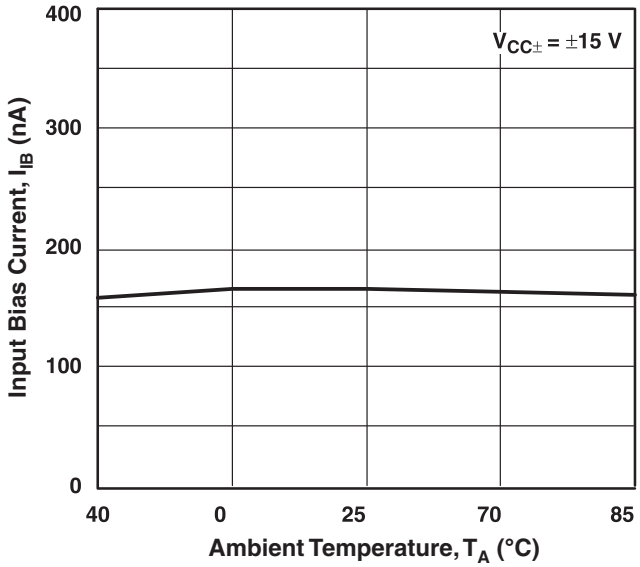

Figure 9.

TYPICAL CHARACTERISTICS (continued)

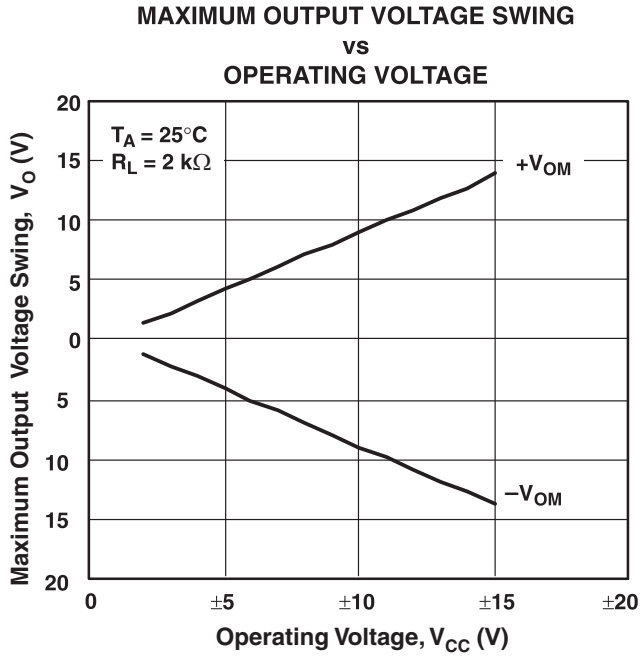

Figure 10.

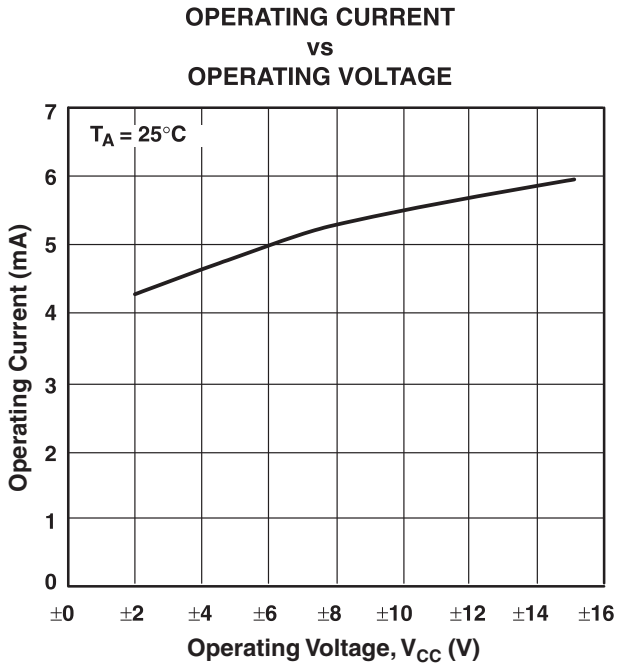

Figure 11.

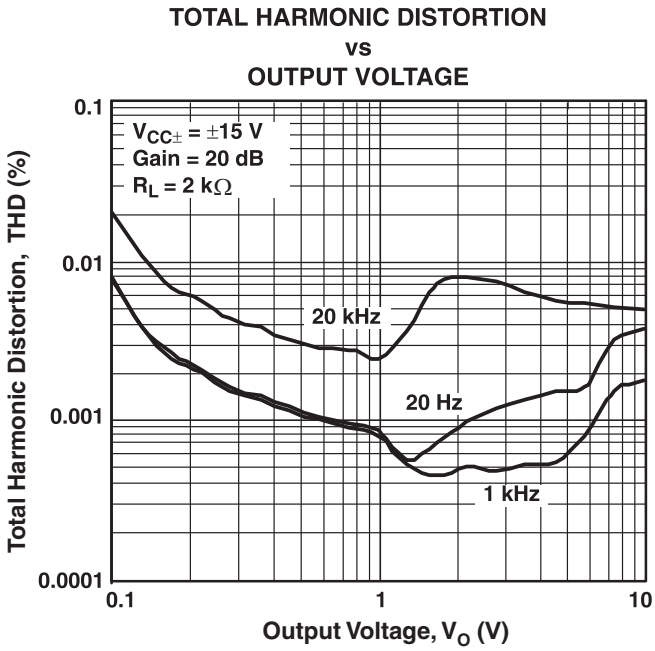

Figure 12.

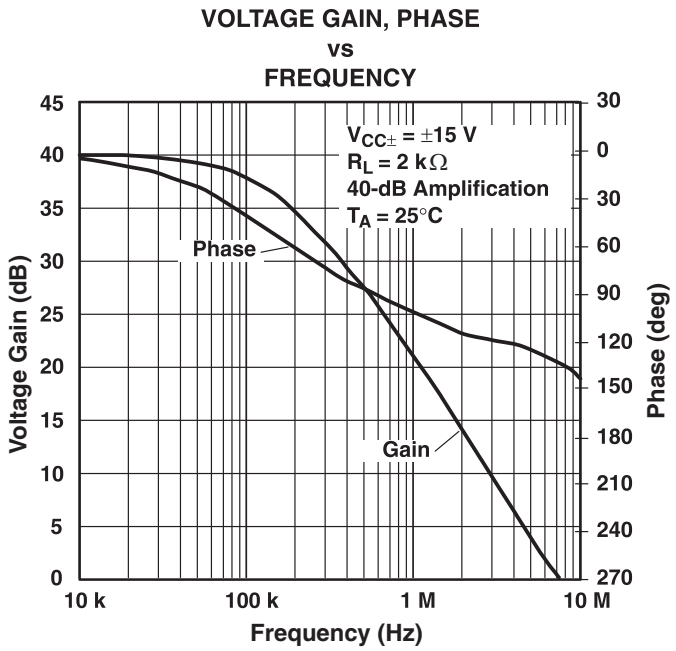

Figure 13.

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REVISION HISTORY

Changes from Original (December 2010) to Revision A **Page**

- Added AEC-Q100 info to the features; changed Suitable for Applications to Suitable for Automotive Applications 1
- Added PW pinout drawing 1
- Added second row for PW package to Ordering Information table 1
- Added ESDS 2
- Changed T_J to T_A 2
- Removed θ_{JA} row from Abs Max table because it is also listed in the thermal table 2
- Added ESD ratings to Abs Max table 2
- Added thermal table 3
- Changed T_A = 25°C to T_A = –40°C to 125°C in condition statement for Elec Char table and Op Char table 3

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
RC4580QDRQ1	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	R4580Q	Samples
RC4580QPWRQ1	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	R4580Q	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

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OTHER QUALIFIED VERSIONS OF RC4580-Q1 :

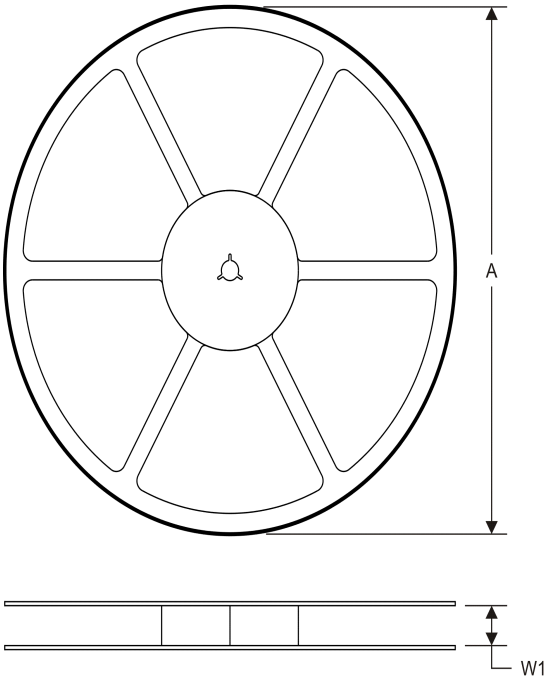
- Catalog: RC4580

NOTE: Qualified Version Definitions:

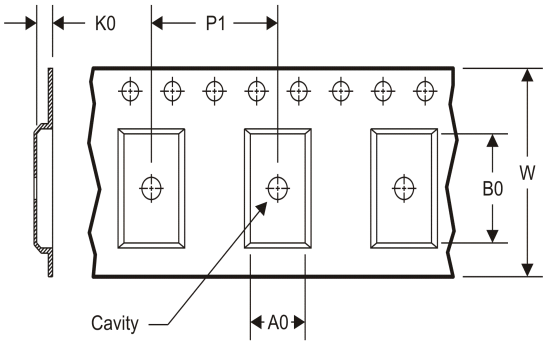
- Catalog - TI's standard catalog product

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



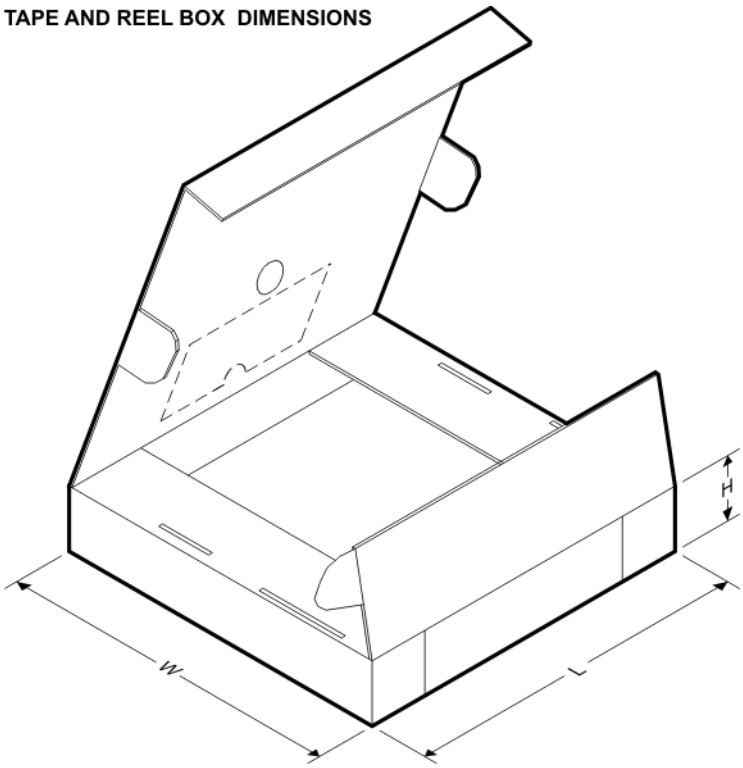
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

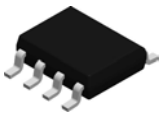
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
RC4580QDRQ1	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
RC4580QPWRQ1	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
RC4580QDRQ1	SOIC	D	8	2500	340.5	338.1	20.6
RC4580QPWRQ1	TSSOP	PW	8	2000	367.0	367.0	35.0

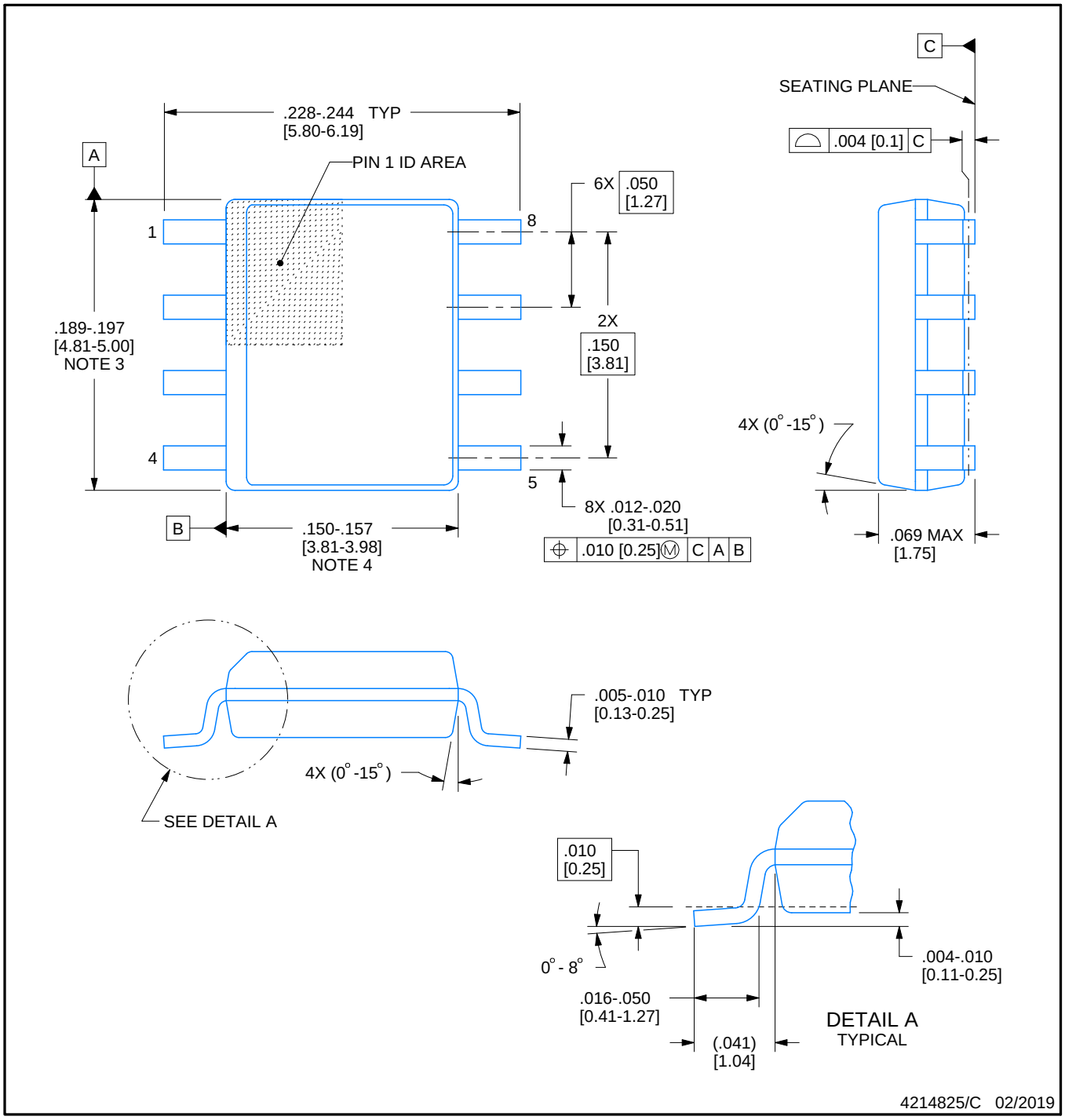


PACKAGE OUTLINE

D0008A

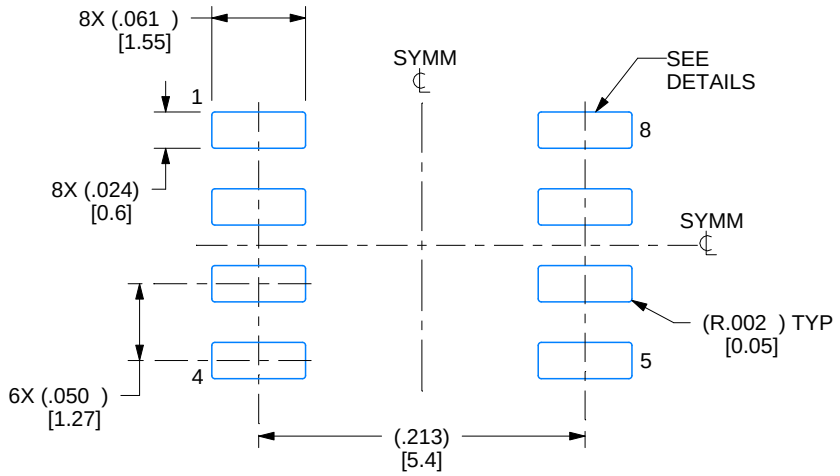
SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT

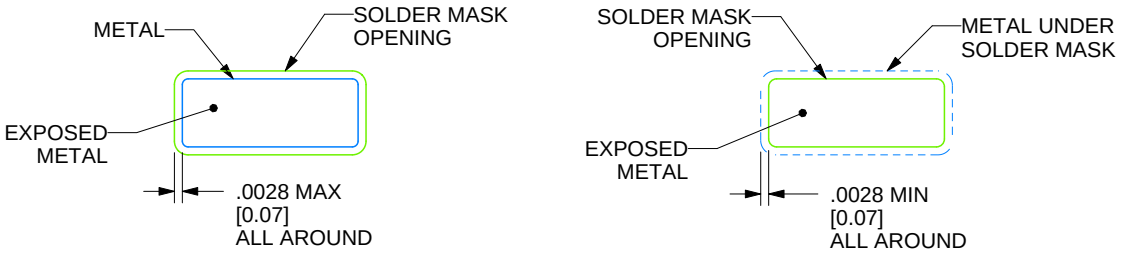


NOTES:

1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
4. This dimension does not include interlead flash.
5. Reference JEDEC registration MS-012, variation AA.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:8X

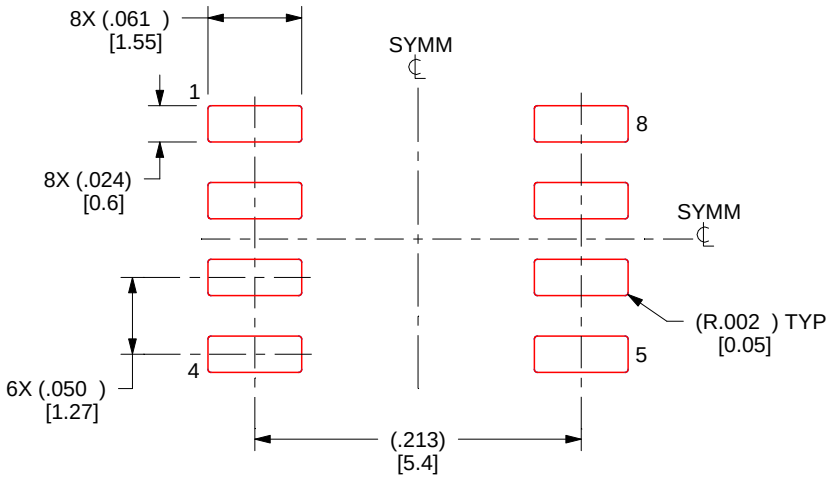


SOLDER MASK DETAILS

4214825/C 02/2019

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

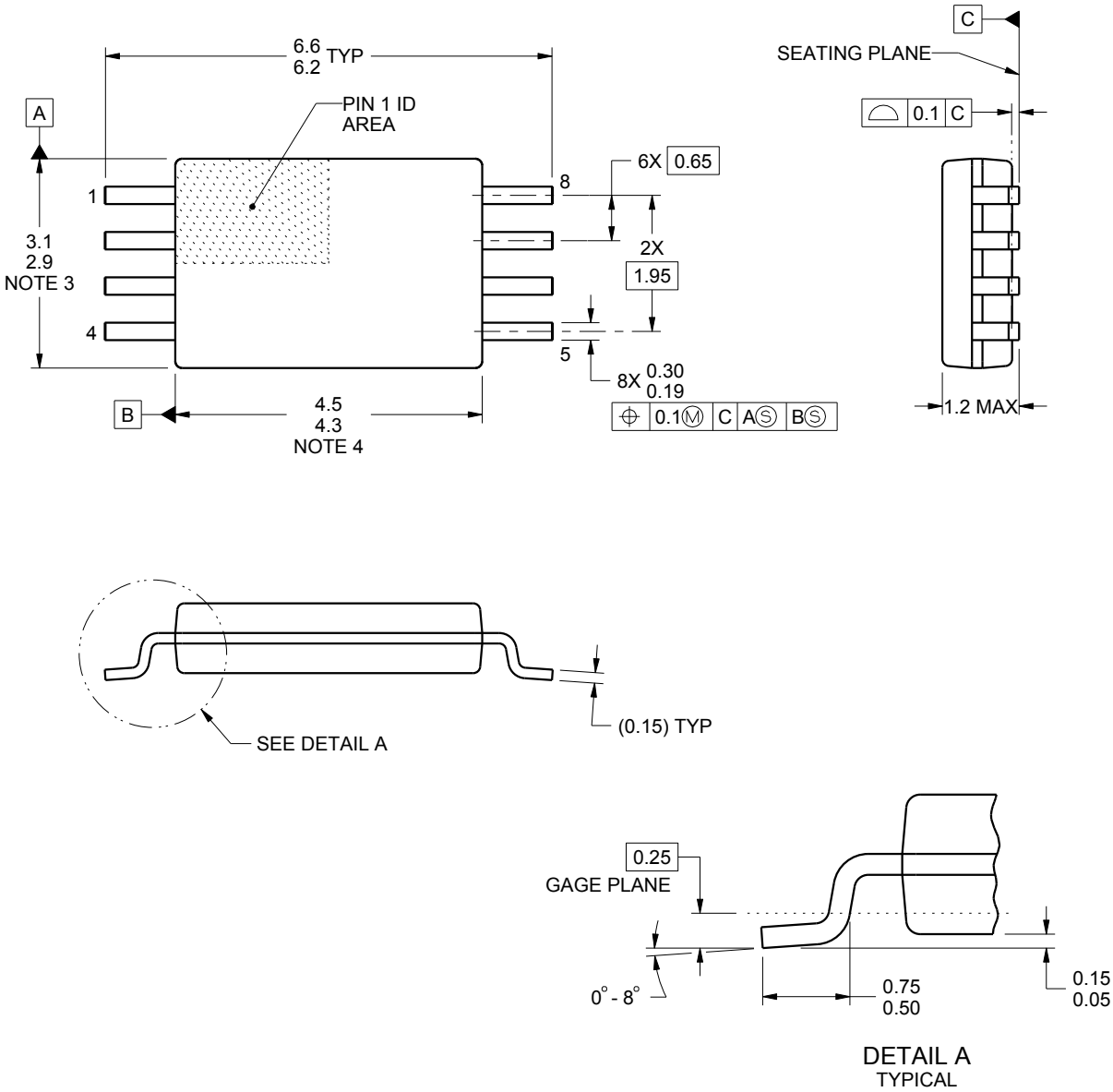


SOLDER PASTE EXAMPLE
BASED ON .005 INCH [0.125 MM] THICK STENCIL
SCALE:8X

4214825/C 02/2019

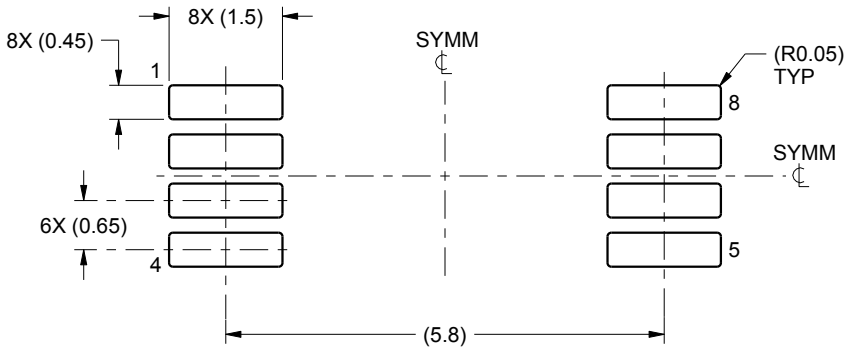
NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

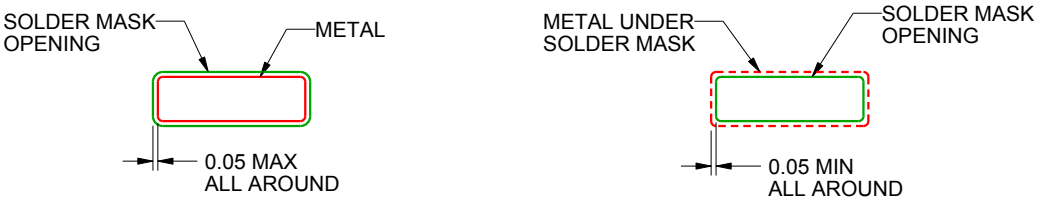


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153, variation AA.



LAND PATTERN EXAMPLE
SCALE:10X



NON SOLDER MASK
DEFINED

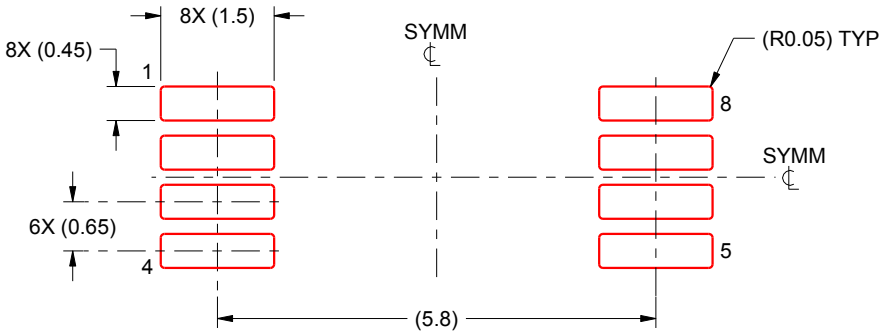
SOLDER MASK
DEFINED

SOLDER MASK DETAILS
NOT TO SCALE

4221848/A 02/2015

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:10X

4221848/A 02/2015

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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